

Excellent Integrated System Limited

Stocking Distributor

Click to view price, real time Inventory, Delivery & Lifecycle Information:

[Texas Instruments](#)
[LM3355MM-4.1/NOPB](#)

For any questions, you can email us directly:

sales@integrated-circuit.com

LM3355 Regulated 50mA Buck-Boost Switched Capacitor DC/DC Converter

Check for Samples: [LM3355](#)

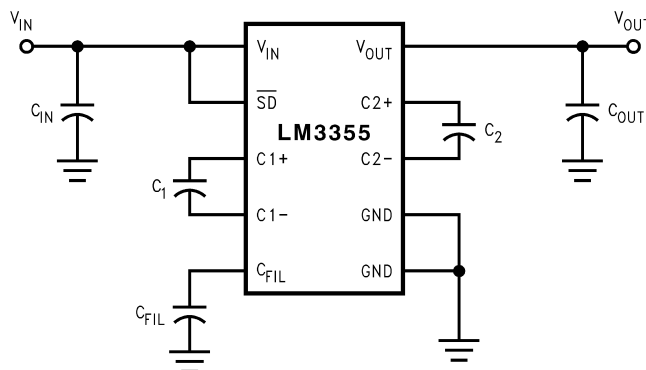
FEATURES

- Regulated V_{OUT} with $\pm 3\%$ Accuracy
- Standard Output Voltage of 4.1V
- Custom Output Voltages Available from 1.8V to 4.1V in 100 mV Increments
- 2.5V to 5.5V Input Voltage
- Up to 50 mA Output Current
- >75% Average Efficiency
- Uses Few, Low-cost External Components
- Very Small Solution Size
- 375 μ A Typical Operating Current
- 2.3 μ A Typical Shutdown Current
- 1 MHz Switching Frequency (Typical)
- Architecture and Control Methods Provide High Load Current and Good Efficiency
- VSSOP-10 Package
- Over-temperature Protection

APPLICATIONS

- White LED Display Backlights
- 1-cell Lilon Battery-operated Equipment Including PDAs, Hand-held PCs, Cellular Phones
- Flat Panel Displays
- Hand-held Instruments
- NiCd, NiMH, or Alkaline Battery Powered Systems

Typical Operating Circuit



DESCRIPTION

The LM3355 is a CMOS switched capacitor DC/DC converter that produces a regulated output voltage by automatically stepping up (boost) or stepping down (buck) the input voltage. It accepts an input voltage between 2.5V and 5.5V. The LM3355 is available with a standard output voltage of 4.1V (ideal for white LED applications). If other output voltage options between 1.8V and 4.1V are desired for other applications, please contact your TI representative.

The LM3355's proprietary buck-boost architecture enables up to 50 mA of load current at an average efficiency greater than 75%. Typical operating current is only 375 μ A and the typical shutdown current is only 2.3 μ A.

The LM3355 is available in a 10-pin VSSOP package. This package has a maximum height of only 1.1 mm.

The high efficiency of the LM3355, low operating and shutdown currents, small package size, and the small size of the overall solution make this device ideal for battery powered, portable, and hand-held applications.

See the LM3352 for up to 200mA of output current.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

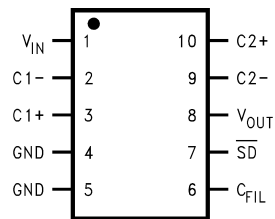
All trademarks are the property of their respective owners.

LM3355

SNVS163D –MAY 2001–REVISED APRIL 2013

www.ti.com

Connection Diagram



**Figure 1. Top View
VSSOP-10 Pin Package
See Package Number DGS0010A**

PIN DESCRIPTIONS

Pin Number	Name	Function
1	V _{IN}	Input Supply Voltage
2	C1-	Negative Terminal for C1
3	C1+	Positive Terminal for C1
4	GND	Ground
5	GND	Ground
6	C _{FIL}	Filter Capacitor, a 1μF capacitor is recommended.
7	\overline{SD}	Shutdown, active low
8	V _{OUT}	Regulated Output Voltage
9	C2-	Negative Terminal for C2
10	C2+	Positive Terminal for C2



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾⁽²⁾

All Pins		-0.5V to 5.6V
Power Dissipation ($T_A = 25^\circ\text{C}$) ⁽³⁾		Internally Limited
T_{JMAX} ⁽³⁾		150°C
θ_{JA} ⁽³⁾		250°C/W
Storage Temperature		-65°C to +150°C
Lead Temperature (Soldering, 5 sec.)		260°C
ESD Rating ⁽⁴⁾	Human Body Model	1.5 kV
	Machine Model	100V

- (1) "Absolute Maximum Ratings" indicate limits beyond which damage to the device may occur. Operating Ratings are conditions for which the device is intended to be functional, but device parameter specifications may not be ensured. For ensured specifications and test conditions, see "Electrical Characteristics".
- (2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.
- (3) As long as $T_A \leq +85^\circ\text{C}$, all electrical characteristics hold true and the junction temperature should remain below +125°C.
- (4) The Human Body Model is a 100 pF capacitor discharged through a 1.5 kΩ resistor into each pin. The Machine Model is a 200 pF capacitor discharged directly into each pin.

OPERATING RATINGS

Input Voltage (V_{IN})	2.5V to 5.5V
Output Voltage (V_{OUT})	1.8V to 4.1V
Ambient Temperature (T_A) ⁽¹⁾	-40°C to +85°C
Junction Temperature (T_J) ⁽¹⁾	-40°C to +125°C

- (1) As long as $T_A \leq +85^\circ\text{C}$, all electrical characteristics hold true and the junction temperature should remain below +125°C.

LM3355

SNVS163D – MAY 2001 – REVISED APRIL 2013

www.ti.com

ELECTRICAL CHARACTERISTICS

Limits in standard typeface are for $T_A = 25^\circ\text{C}$, and limits in **boldface** type apply over the full operating temperature range of $-40^\circ\text{C} \leq T_A \leq 85^\circ\text{C}$. Unless otherwise specified: $C_1 = C_2 = 0.33 \mu\text{F}$; $C_{\text{IN}} = 10 \mu\text{F}$; $C_{\text{OUT}} = 10 \mu\text{F}$; $C_{\text{FIL}} = 1 \mu\text{F}$; $V_{\text{IN}} = 3.5\text{V}$.

Parameter	Conditions	Min ⁽¹⁾	Typ ⁽²⁾	Max ⁽¹⁾	Units
LM3355-4.1					
Output Voltage (V_{OUT})	$V_{\text{IN}} = 3.5\text{V}$; $I_{\text{LOAD}} = 50 \text{ mA}$	4.038	4.1	4.162	V
	$2.6\text{V} < V_{\text{IN}} < 5.5\text{V}$; $1 \text{ mA} < I_{\text{LOAD}} < 50 \text{ mA}$	3.977/ 3.936	4.1	4.223/ 4.264	
	$2.5\text{V} < V_{\text{IN}} < 5.5\text{V}$; $1 \text{ mA} < I_{\text{LOAD}} < 40 \text{ mA}$	3.977/ 3.936	4.1	4.223/ 4.264	
Efficiency	$I_{\text{LOAD}} = 10 \text{ mA}$		80		%
	$I_{\text{LOAD}} = 50 \text{ mA}$		75		
Output Voltage Ripple (Peak-to-Peak)	$I_{\text{LOAD}} = 50 \text{ mA}$ $C_{\text{OUT}} = 10 \mu\text{F}$ ceramic		75		mV _{P-P}
LM3355-ALL OUTPUT VOLTAGE VERSIONS					
Operating Quiescent Current	Measured at Pin V_{IN} ; $I_{\text{LOAD}} = 0\text{A}$ ⁽³⁾		375	475	μA
Shutdown Quiescent Current	SD Pin at 0V ⁽⁴⁾		2.3	5	μA
Switching Frequency		0.60	1	1.40	MHz
SD Input Threshold Low	$2.5\text{V} < V_{\text{IN}} < 5.5\text{V}$			0.2 V_{IN}	V
SD Input Threshold High	$2.5\text{V} < V_{\text{IN}} < 5.5\text{V}$	0.8 V_{IN}			V
SD Input Current	Measured at SD Pin; SD Pin = $V_{\text{IN}} = 5.5\text{V}$		0.3		μA

- (1) All limits specified at room temperature (standard typeface) and at temperature extremes (bold typeface). All room temperature limits are 100% tested or specified through statistical analysis. All limits at temperature extremes are specified by correlation using standard Statistical Quality Control methods (SQC). All limits are used to calculate Average Outgoing Quality Level (AOQL).
- (2) Typical numbers are at 25°C and represent the most likely norm.
- (3) The V_{OUT} pin is forced to 200 mV above the typical V_{OUT} . This is to insure that the internal switches are off.
- (4) The output capacitor C_{OUT} is fully discharged before measurement.

TYPICAL PERFORMANCE CHARACTERISTICS

Unless otherwise specified $T_A = 25^\circ\text{C}$.

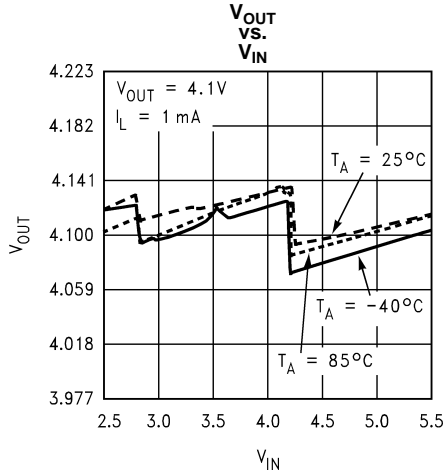


Figure 2.

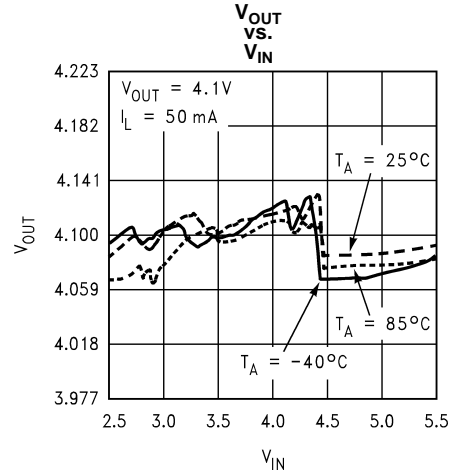


Figure 3.

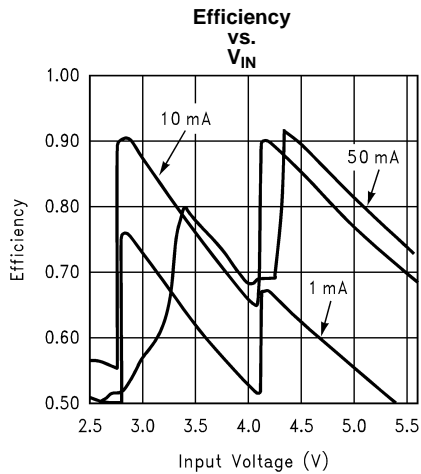


Figure 4.

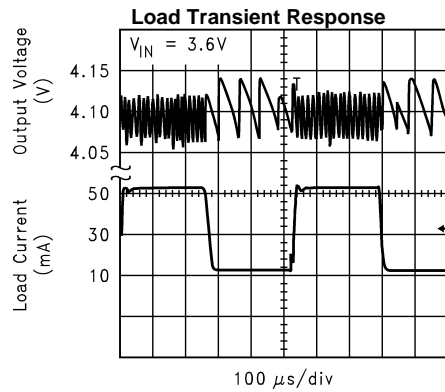


Figure 5.

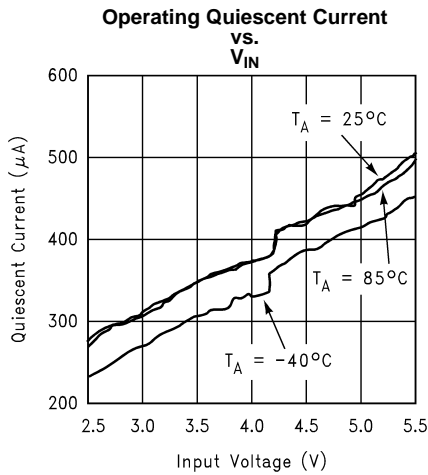


Figure 6.

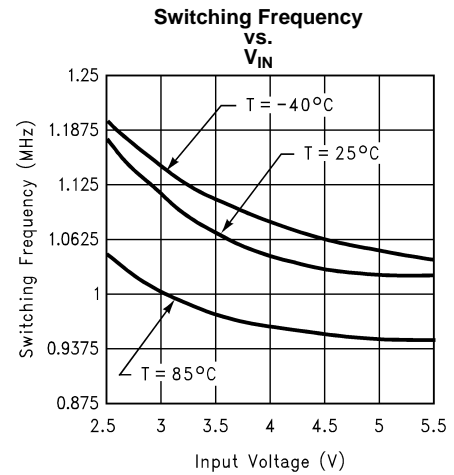


Figure 7.

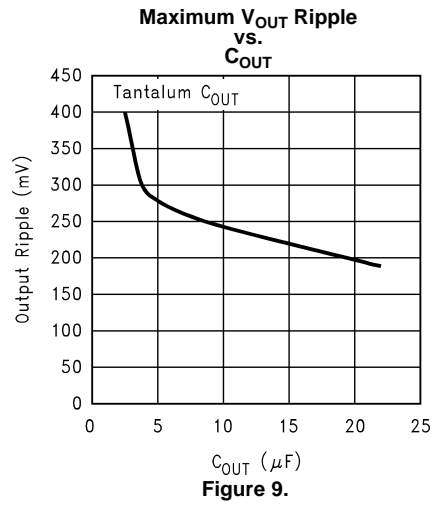
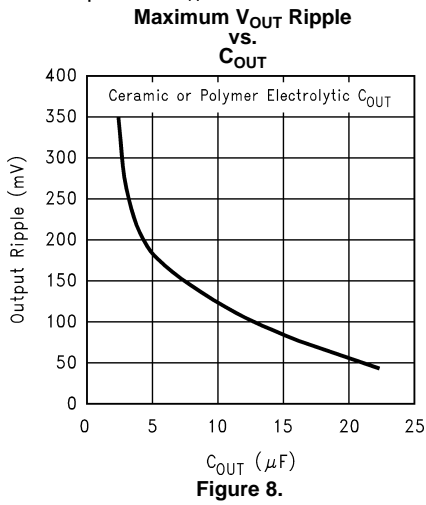
LM3355

SNVS163D –MAY 2001 –REVISED APRIL 2013

www.ti.com

TYPICAL PERFORMANCE CHARACTERISTICS (continued)

Unless otherwise specified $T_A = 25^\circ\text{C}$.



APPLICATIONS INFORMATION

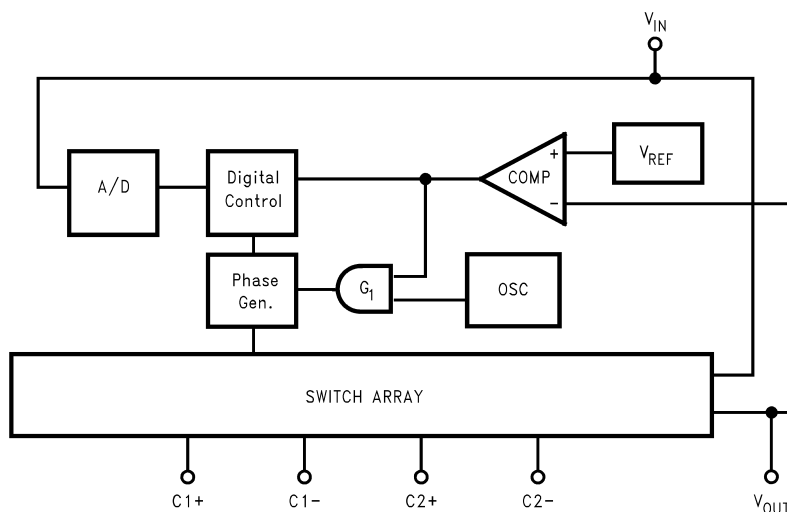


Figure 10. Block Diagram

Operating Principle

The LM3355 is designed to provide a step-up/step-down voltage regulation in battery powered systems. It combines switched capacitor circuitry, reference, comparator, and shutdown logic in a single 10-pin VSSOP package. The LM3355 can provide a regulated voltage between 1.8V and 4.1V from an input voltage between 2.5V and 5.5V. It can supply a load current up to 50 mA.

As shown in Figure 10, the LM3355 employs two feedback loops to provide regulation in the most efficient manner possible. The first loop is from V_{OUT} through the comparator COMP, the AND gate G_1 , the phase generator, and the switch array. The comparator's output is high when V_{OUT} is less than the reference V_{REF} . Regulation is provided by gating the clock to the switch array. In this manner, charge is transferred to the output only when needed. The second loop controls the gain configuration of the switch array. This loop consists of the comparator, the digital control block, the phase generator, and the switch array. The digital control block computes the most efficient gain from a set of five gains based on inputs from the A/D and the comparator. The gain signal is sent to the phase generator which then sends the appropriate timing and configuration signals to the switch array. This dual loop provides regulation over a wide range of loads efficiently.

Since efficiency is automatically optimized, the curves for V_{OUT} vs. V_{IN} and Efficiency vs. V_{IN} in the [Typical Performance Characteristics](#) section exhibit small variations. The reason is that as input voltage or output load changes, the digital control loops are making decisions on how to optimize efficiency. As the switch array is reconfigured, small variations in output voltage and efficiency result. In all cases where these small variations are observed, the part is operating correctly; minimizing output voltage changes and optimizing efficiency.

Charge Pump Capacitor Selection

A 0.33 μF ceramic capacitor is suggested for C1 and C2. To ensure proper operation over temperature variations, an X7R dielectric material is recommended.

Filter Capacitor Selection

CAPACITOR TECHNOLOGIES

The three major technologies of capacitors that can be used as filter capacitors for LM3355 are:

1. tantalum
2. ceramic
3. polymer electrolytic technologies

LM3355

SNVS163D –MAY 2001 –REVISED APRIL 2013

www.ti.com

Tantalum

Tantalum capacitors are widely used in switching regulators. Tantalum capacitors have the highest CV rating of any technology; as a result, high values of capacitance can be obtained in relatively small package sizes. It is also possible to obtain high value tantalum capacitors in very low profile (<1.2 mm) packages. This makes the tantalums attractive for low-profile, small size applications. Tantalums also possess very good temperature stability; i.e., the change in the capacitance value, and impedance over temperature is relatively small. However, the tantalum capacitors have relatively high ESR values which can lead to higher voltage ripple and their frequency stability (variation over frequency) is not very good, especially at high frequencies (>1 MHz).

Ceramic

Ceramic capacitors have the lowest ESR of the three technologies and their frequency stability is exceptionally good. These characteristics make the ceramics an attractive choice for low ripple, high frequency applications. However, the temperature stability of the ceramics is bad, except for the X7R and X5R dielectric types. High capacitance values (>1 μ F) are achievable from companies such as Taiyo-yuden which are suitable for use with regulators. Ceramics are taller and larger than the tantalums of the same capacitance value.

Polymer Electrolytic

Polymer electrolytic is a third suitable technology. Polymer capacitors provide some of the best features of both the ceramic and the tantalum technologies. They provide very low ESR values while still achieving high capacitance values. However, their ESR is still higher than the ceramics, and their capacitance value is lower than the tantalums of the same size. Polymers offer good frequency stability (comparable to ceramics) and good temperature stability (comparable to tantalums). The Aluminum Polymer Electrolytics offered by Cornell-Dubilier and Panasonic, and the POSCAPs offered by Sanyo fall under this category.

Table 1 compares the features of the three capacitor technologies.

Table 1. Comparison of Capacitor Technologies

	Ceramic	Tantalum	Polymer Electrolytic
ESR	Lowest	High	Low
Relative Height	Low for Small Values (<10 μ F); Taller for Higher Values	Lowest	Low
Relative Footprint	Large	Small	Largest
Temperature Stability	X7R/X5R-Acceptable	Good	Good
Frequency Stability	Good	Acceptable	Good
V _{OUT} Ripple Magnitude @ <50 mA	Low	High	Low
V _{OUT} Ripple Magnitude @ >100 mA	Low	Slightly Higher	Low
dv/dt of V _{OUT} Ripple @ All Loads	Lowest	High	Low

CAPACITOR SELECTION

Output Capacitor (C_{OUT})

The output capacitor C_{OUT} directly affects the magnitude of the output ripple voltage so C_{OUT} should be carefully selected. The graphs titled V_{OUT} Ripple vs. C_{OUT} in the [Typical Performance Characteristics](#) section show how the ripple voltage magnitude is affected by the C_{OUT} value and the capacitor technology. These graphs are taken at the gain at which worst case ripple is observed. In general, the higher the value of C_{OUT}, the lower the output ripple magnitude. At lighter loads, the low ESR ceramics offer a much lower V_{OUT} ripple than the higher ESR tantalums of the same value. At higher loads, the ceramics offer a slightly lower V_{OUT} ripple magnitude than the tantalums of the same value. However, the dv/dt of the V_{OUT} ripple with the ceramics and polymer electrolytics is much lower than the tantalums under all load conditions. The tantalums are suggested for very low profile, small size applications. The ceramics and polymer electrolytics are a good choice for low ripple, low noise applications where size is less of a concern.

Input Capacitor (C_{IN})

The input capacitor C_{IN} directly affects the magnitude of the input ripple voltage, and to a lesser degree the V_{OUT} ripple. A higher value C_{IN} will give a lower V_{IN} ripple. To optimize low input and output ripple as well as size a 10 μ F polymer electrolytic or ceramic, or 15 μ F tantalum capacitor is recommended. This will ensure low input ripple at 50 mA load current. If lower currents will be used or higher input ripple can be tolerated then a smaller capacitor may be used to reduce the overall size of the circuit. The lower ESR ceramics and polymer electrolytics achieve a lower V_{IN} ripple than the higher ESR tantalums of the same value. Tantalums make a good choice for small size, very low profile applications. The ceramics and polymer electrolytics are a good choice for low ripple, low noise applications where size is less of a concern. The 10 μ F polymer electrolytics are physically much larger than the 15 μ F tantalums and 10 μ F ceramics.

C_{FIL}

A 1 μ F, X7R ceramic capacitor should be connected to pin C_{FIL} . This capacitor provides the filtering needed for the internal supply rail of the LM3355.

Of the different capacitor technologies, a sample of vendors that have been verified as suitable for use with the LM3355 are shown in [Table 2](#).

Table 2. Capacitor Vendor Information

	Manufacturer	Tel	Fax	Website
Ceramic	Taiyo-yuden	(408) 573-4150	(408) 573-4159	www.t-yuden.com
	AVX	(803) 448-9411	(803) 448-1943	www.avxcorp.com
Tantalum	Sprague/Vishay	(207) 324-4140	(207) 324-7223	www.vishay.com
	Nichicon	(847) 843-7500	(847) 843-2798	www.nichicon.com
Polymer Electrolytic	Cornell-Dubilier (ESRD)	(508) 996-8561	(508) 996-3830	www.cornell-dubilier.com
	Sanyo (POSCAP)	(619) 661-6322	(619) 661-1055	www.sanyovideo.com

Thermal Protection

During output short circuit conditions, the LM3355 will draw high currents causing a rise in the junction temperature. On-chip thermal protection circuitry disables the charge pump action once the junction temperature exceeds the thermal trip point, and re-enables the charge pump when the junction temperature falls back to a safe operating point.

LM3355

SNVS163D –MAY 2001–REVISED APRIL 2013

www.ti.com

Typical Application Circuits

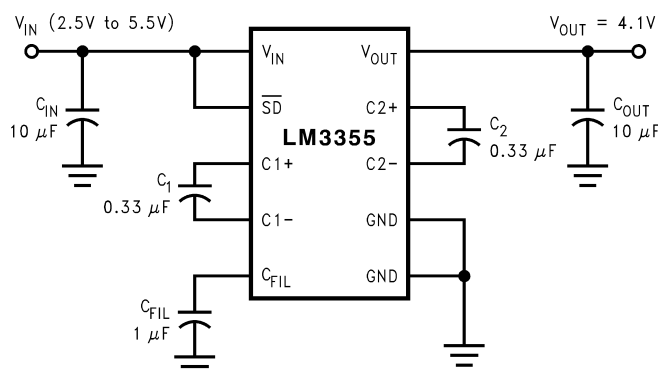


Figure 11. Basic Buck/Boost Regulator

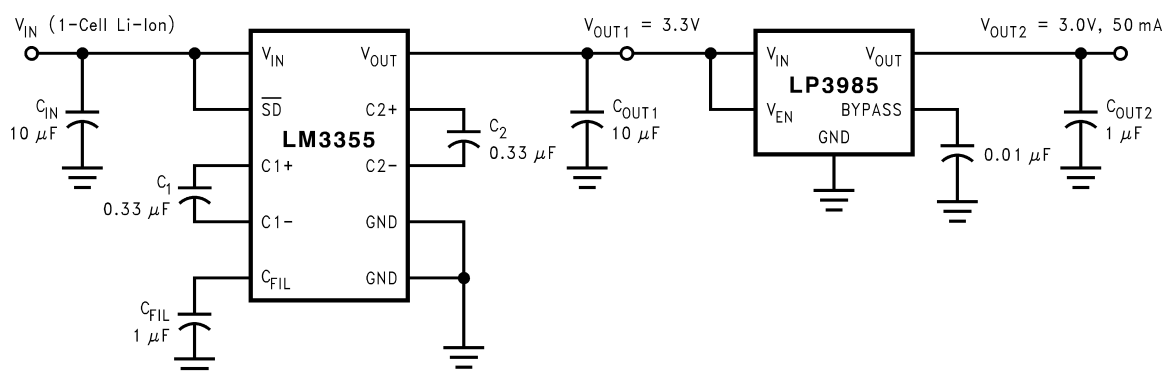


Figure 12. Low Output Noise and Ripple Buck/Boost Regulator

Layout Considerations

Due to the 1 MHz typical switching frequency of the LM3355, careful board layout is a must. It is important to place the capacitors as close to the IC as possible and to keep the traces between the capacitors and the IC short and direct. Use of a ground plane is recommended.

REVISION HISTORY

Changes from Revision C (April 2013) to Revision D	Page
• Changed layout of National Data Sheet to TI format	10

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community

e2e.ti.com